WHAT IS CLAIMED IS:

1. A device comprising:

a first portion of an inductor disposed in a first layer of a multilayer substrate;

a second portion of the inductor disposed in a second layer of the multilayer substrate, the second portion coupled to the first portion; and

a shielding plane disposed between the first portion and the second portion.

2. A device according to Claim 1, wherein the shielding plane comprises a ground plane.

3. A device according to Claim 1, wherein current is to flow in a first direction in the first portion of the inductor and in a second direction opposite to the first direction in the second portion of the inductor.

4. A device according to Claim 1, further comprising:

a third portion of the inductor disposed in a third layer of the multilayer substrate, the third portion coupled to the second portion; and

a second shielding plane disposed between the second portion and the third portion.

5. A device according to Claim 1, wherein the inductor comprises a spiral turn inductor.

6. A device according to Claim 1, further comprising:

a via to couple the first portion to the second portion.

7. A device according to Claim 1, further comprising:

a pin-through hole to couple the first portion to the second portion.

8. A device according to Claim 1, further comprising:

a dielectric disposed between the first layer and the shielding plane and between the second layer and the shielding plane.

9. A method comprising:

fabricating a first layer of a multilayer substrate comprising a first portion of an inductor;

fabricating a second layer of the multilayer substrate above the first layer, the second layer comprising a shielding plane; and

fabricating a third layer of the multilayer substrate above the second layer, the third layer comprising a second portion of the inductor,

wherein the second layer comprises a coupling to electrically couple the first portion of the inductor to the second portion of the inductor.

10. A method according to Claim 9, wherein the shielding plane comprises a ground plane.

11. A method according to Claim 9, wherein current is to flow in a first direction in the first portion of the inductor and in a second direction opposite to the first direction in the second portion of the inductor.

12. A method according to Claim 9, further comprising:

fabricating a fourth layer of the multilayer substrate above the third layer, the fourth layer comprising a second shielding plane; and

fabricating a fifth layer of the multilayer substrate above the fourth layer, the fifth layer comprising a third portion of the inductor,

wherein the fourth layer comprises a second coupling to electrically couple the second portion of the inductor to the third portion of the inductor.

13. A system comprising:

an integrated circuit package comprising:

a first portion of an inductor disposed in a first layer of the integrated circuit package;

a second portion of the inductor disposed in a second layer of the integrated circuit package, the second portion coupled to the first portion; and

a shielding plane disposed between the first portion and the second portion; and

a double data rate memory in communication with the integrated circuit package.

14. A system according to Claim 13, further comprising:

an integrated circuit die coupled to the integrated circuit package, the integrated circuit package to transmit data between the integrated circuit die and the memory.

15. A system according to Claim 13, wherein the shielding plane comprises a ground plane.

16. A system according to Claim 13, wherein current is to flow in a first direction in the first portion of the inductor and in a second direction opposite to the first direction in the second portion of the inductor.

17. A system according to Claim 13, further comprising:

a third portion of the inductor disposed in a third layer of the multilayer substrate, the third portion coupled to the second portion; and

a second shielding plane disposed between the second portion and the third portion.